

IN THE SPECIFICATION:

Please ~~replace~~<sup>✓</sup> the Abstract of the Disclosure with the amended one shown below in clean form for clarity. A version with markings to show the changes made is also attached herein.

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A method and apparatus are disclosed for mounting a wafer on a mount and thinning the wafer. The wafer includes a front surface having bumps with an adhesive tape having a backing attached thereto and a back surface. The front surface of the wafer is mounted facedown on a suction surface with the backing of the adhesive tape abutting the surface. The wafer is then suctioned, after which the back surface of the wafer undergoes a grinding process to thin the wafer. Since the backing attached to the bumps on the wafer is substantially planar and sits substantially flat on the suction surface of the wafer mount, the force exerted on the wafer from the thinning process does not overcome the suction force holding the wafer on the wafer mount. Thus, the bumped wafer may be thinned without damaging the bumps and the active surface of the wafer.

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